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U.S. Department of Commerce

	FORM COVER:	
PATENTS ONL'	10360	1700ISON.0021
To the Honorable		Please record the attached original documents or copy thereof.
1. Name of Co.	nveying Party(ies):	2. Name and Address of Receiving Party(ies):
(1) NOE MIY (2) KOJI SEC (3) MATSUO	AND	Name: Hitachi Plant Technologies, Ltd. Address: 5-2, Higashi-Ikebukuro 4-chome, Toshima-ku City: Tokyo 170-8466 Japan
Additional names 3. Nature of Co	of conveying parties attached: Yes No	
	•	
	nte: (1) and (3) June 15, 2010 (2) June 14, 2010	
4. (a) Patent A	pplication Number(s):	4. (b) Patent Numbers:
the execution dat	is being filed together with a new application, e of the application is: Tumbers Attached.	·
	Address of Party to whom Correspondence Document Should be Mailed:	6. Total Number of Applications and Patents Involved: 1
Name:	Juan Carlos A. Marquez	7. Total Fee: \$40.00 (37 C.F.R. § 3.41)
Address:	Stites & Harbison PLLC 1199 North Fairfax Street Suite 900 Alexandria, VA 22314	 Enclosed. Authorized to be charged to deposit account.
		8. Deposit Account Number: 12-0555
DO NOT USE T	THIS SPACE	
9. Statement	and Signature:	
To the best original documen		rue and correct and any attached copy is a true copy of the
		June 24, 2010
Juan Carlos A. N	Marquez, Registration No. 34,072	Control of the contro
•	pages comprising cover sheet: 1	
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ASSIGNMENT (譲 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi Plant Technologies, Ltd., a corporation organized under the laws of Japan, located at 5-2, Higashi-Ikebukuro 4-chome, Toshima-ku, Tokyo 170-8466, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi Plant Technologies, Ltd., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SAMPLE COLLECTOR

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi Plant Technologies, Ltd., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee:

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi Plant Technologies, Ltd..

Signed on the date(s) indicated aside signatures:

Date Signed (署名日)
15. jun. 2010
14. jun 2010
15 jun 2010
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